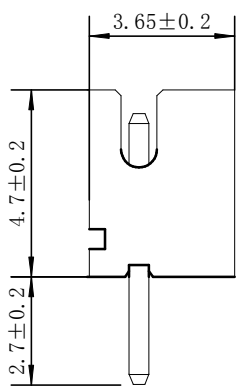
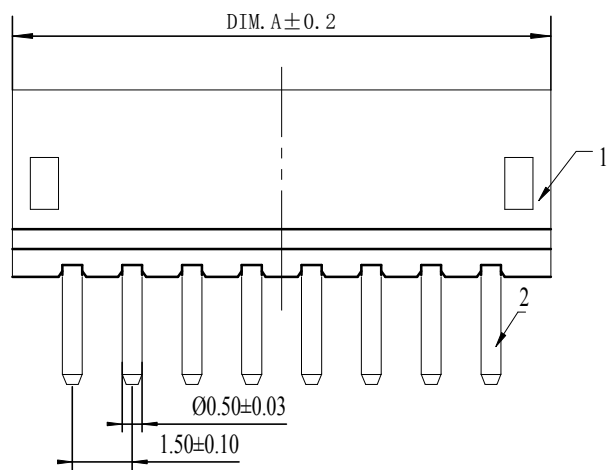
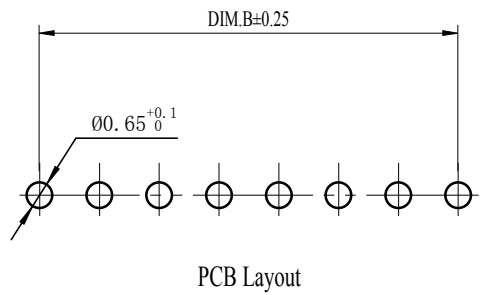
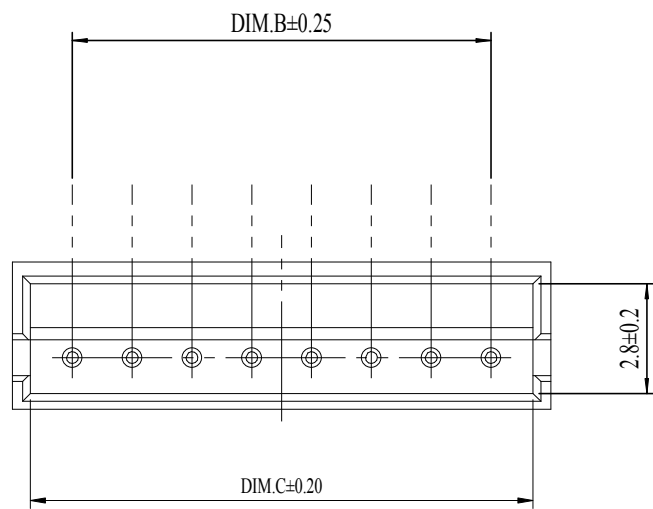


REV.	EC#	DESCRIPTION	DATE	DRAWN	CHECK	APPROVED
1.00		初版发行	2018-04-22			



适应基板厚度: 1.2mm~1.6mm
 温度范围: -25℃~85℃
 额定电压: 250V AC/DC
 额定电流: 1A
 绝缘电阻: ≥1000MΩ
 耐压: 800V AC/minute

15	24.00	21.00	23.10
14	22.50	19.50	21.60
13	21.00	18.00	20.10
12	19.50	16.50	18.60
11	18.00	15.00	17.10
10	16.50	13.50	15.60
9	15.00	12.00	14.10
8	13.50	10.50	12.60
7	12.00	9.00	11.10
6	10.50	7.50	9.60
5	9.00	6.00	8.10
4	7.50	4.50	6.60
3	6.00	3.00	5.10
2	4.50	1.50	3.60
Pin	DIM.A	DIM.B	DIM.C

2	PIN	n PCS	材质: 黄铜, 电镀: 镀亮锡60u~MIN
1	Housing	1 PCS	材质: PA66 颜色: 本色或黑色
NO.	NAME	QTY	DESCRIPTION

深圳市虹成电子有限公司

DRAW:	瞿寿坤	2018-04-22	TITLE:	WAFER 1.5ZHA 立式 DIP	DRAW NAME:	HCZZ0445-8			
DESIGN:	瞿寿坤	2018-04-22	CHECK:	胡海萍	SERIES:	1502 SERIES	DRAW NO.		
APPROVED	胡海萍	2018-04-22	P/N:		UNIT:	mm	SHEET:	1/1	
CUSTOMER DRAWING			REV.	1.00	SCALE	N/A			

技术要求:

- 1) 材质: 见附表;
- 2) 电镀: 见附表;
- 3) 塑件表面平整、光洁、无毛刺、气泡、烧焦、变形、浇口无拉伤、多料或缺料等不良现象;
- 4) 端子表面无氧化、电镀不良等现象。

GENERAL TOLERANCES			
DIM	TOL	DIM	DEG
X		X°	±3.00°
X.X	±0.35	X.X°	±2.00°
X.XX	±0.25	X.XX°	±1.00°
X.XXX	±0.15	X.XXX°	